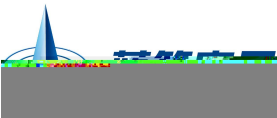


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!"#\$%&'()* (##### ' (%))** (



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!"#\$%&'()*+,-./:;<=>?@A B C D E F G H I J K L M N O P Q R S T U V W X Y Z [\] ^ _ ` { | } ~ ¡ ¢ £ ¤ ¥ ¦ § ¨ © ª « ¬ ® ¯ ° ± ² ³ ´ µ ¶ · ¸ ¹ º » ¼ ½ ¾ ¿

1. 塑封封装双 半导体三极管。

1676%48#9 : 9#3; 8111&43#68#; #<\$='>?># : 7; 1&6%#: ; %@; A !#

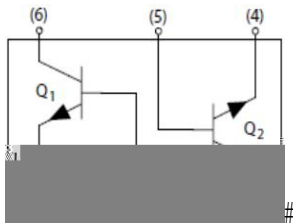
2. 与 互补。无卤产品。

B45 , 7 5 8&; 3C#; ; 63# / 6&+#" DEFF) G<! H I #: 34JK%&!#

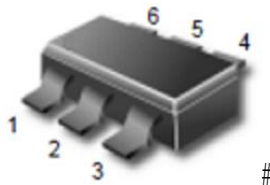
3. 用于功率放大电路。

: 4 / 3#; 5 , 7606 3#; , , 76%; &648!#

4. 1. 塑封封装双 半导体三极管。



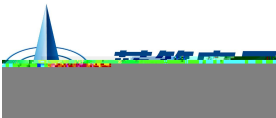
5. 1. 塑封封装双 半导体三极管。



: L9#*、M : N56&& 3# # : L9#(、F : " ; 1 # # : L9#>、? : B477 %&43#
#

6. 1. 塑封封装双 半导体三极管。

+ _I N#B7; 11606%; &6481# <C5 247#	"#	B#	D#
+ _I N# ; 8A #	EFO*?)#	*()0())#	*?)0>))#
P ; 3@68A#	HQ*"#	HQ*B##	HQ*D#

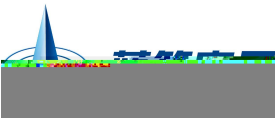


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&

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:;3;5 & 3#	<C5247#	;88A#	R888#
B477 %&43#&4#" ;1 #S47&;A #	S _B "\$#	M)#	S#
B477 %&43#&4#N56&& 3#S47&;A #	S _{BN} \$#	(F#	S#

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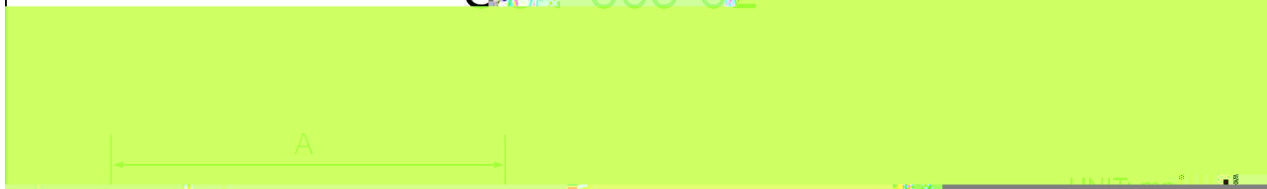
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SOT-363-6I

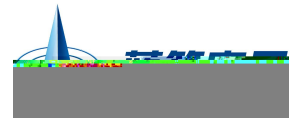


E	1.95	2.25
F	0.20 Typ	



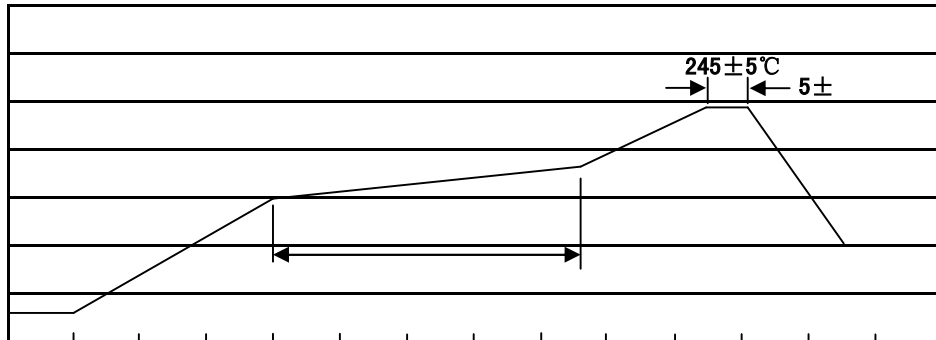
L	0.535 Typ
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!"#\$%&'()*+,-./:;<=>?@A B C D E F G H I J K L M N O P Q R S T U V W X Y Z [\] ^ _ ` { | } ~ ¡ ¢ £ ¤ ¥ ¦ § ¨ © ª « ¬ ® ¯ ° ± ² ³ ´ µ ¶ · ¸ ¹ º » ¼ ½ ¾

J L&+&& Temperature Profile for IR Reflow Soldering(Pb-Free)



94#
* *F) *E) ?)]1 %c# # # *! :3 + ;&8A-*F)O*E)°Ca#=#5 -?)O])1 %!#
((MF±F F±)!F1 %c# # (! : ;@# = 5 ,!-(MF±F°Ca#DK3 ;&48-F±)!F1 %!#
> (*)°C.1 %!# # # # >! B447&8A#<, J-#(O*)°C.1 %!#
#

&&+&&& , /.<:=2,&<3&%390,1.=A&) , :<&(, /<&83=0.<.3=/&

(?)±F°C# # *)±*#1 %!# # # # = 5 ,!-(?)dF°C# # =65 -*)d*#1 %#

&&+&&& E:2@:A.=A&%E*8P&

##.## NN`#

: ;%@;A #=C, # #	R8&1 #					D65 81&48# # [K8& 5 5`#		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
SOT-363	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

&&+&&& Q3<.2, /&